IN THE CLAIMS

1. (Currently Amended) A junction structure for conductive projection, comprising:

a first insulating layer;

a conductor portion formed on a surface of the first insulating layer;

a conductive projection joined to a top surface of the conductor portion ~~which is formed on a surface of an insulating layer,~~;

a second insulating layer formed on the surface of the first insulating layer, the second insulating layer having a top surface that is formed at approximately the same level as the top surface of the conductor portion; and

a resin material extending from the conductive projection to another conductive projection, a portion of the resin material surrounding a root portion of the conductive projection in a ring form, the resin material being of a different material than the second insulating material.

~~wherein said conductive projection is joined to the surface of said conductor portion which is formed at the same level as that of the surface of said insulating layer, and a root portion of said conductive projection is surrounded by a resin material in a ring form.~~

2. (Original) The junction structure for conductive projection according to claim 1, wherein said resin material which surrounds said root portion of said conductive projection is in a fillet form.

3. (Original) The junction structure for conductive projection according to claim 1, wherein said resin material contains an activator which assists the junction between said conductive projection and said conductor portion when said resin material is in an uncured state.

4. (Original) The junction structure for conductive projection according to claim 1, wherein said resin material has photocuring property.

5. (Original) The junction structure for conductive projection according to claim 1, wherein said conductive projection comprises a core portion and a conductive surface layer portion for covering the surface of said core portion.

6. (Withdrawn) A junction method for conductive projection, comprising the steps of:

forming a conductor portion on an insulating layer in such a way that the surface of said conductor portion is formed at the same level as that of the surface of said insulating layer;

supplying a resin material in an uncured state onto at least a junction plane of said conductor portion to which a conductive projection is joined;

disposing said conductive projection on said junction plane which has said resin material supplied thereon; and

heating said resin material and said conductive projection to join said conductive projection to said conductor portion while curing said resin material so as that a root portion of said conductive projection is surrounded by said resin material in a ring form.

7. (Withdrawn) The junction method for conductive projection according to claim 6, wherein said resin material in an uncured state is supplied onto the entire surfaces of both of said conductor portion and said insulating layer, and cured by exposure while excluding the resin material on said junction plane, said conductive projection is disposed on said junction plane on which said resin material remains uncured, and said resin material and said conductive projection are heated.